

ABSTRACT OF THE DISCLOSURE

A method of forming high resolution electronic circuits (10) on a substrate (12) is provided. The method includes the steps of laminating a dielectric layer (14) on a substrate (12), laser drilling channels (16 and 18) in the dielectric film (14) and the substrate (12), and filling channels (16 and 18) with a filler material (20). Further, a release layer (22) is applied to dielectric film layer (14) and filler material (20), the release layer (22) having an adhesive thereon. Release layer (22) is peeled or otherwise removed from substrate (12), leaving filler material (20) formed and shaped on substrate (12), thus producing a high resolution electronic circuit on substrate (12).